

V_{DRM}	=	5200 V
$I_{T(AV)M}$	=	3875 A
$I_{T(RMS)}$	=	6090 A
I_{TSM}	=	55×10^3 A
V_{TO}	=	1.03 V
r_T	=	0.16 mW

Phase Control Thyristor

5STP 34Q5200

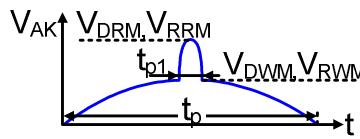
Doc. No. 5SYA1052-02 May 07

- Patented free-floating silicon technology
- Low on-state and switching losses
- Designed for traction, energy and industrial applications
- Optimum power handling capability
- Interdigitated amplifying gate

Blocking

Maximum rated values ¹⁾

Parameter	Symbol	Conditions	5STP 34Q5200		Unit
Max. surge peak forward and reverse blocking voltage	V_{DSM}, V_{RSM}	$t_p = 10$ ms, $f = 5$ Hz $T_{vj} = 5 \dots 125^\circ\text{C}$, Note 1	5200		V
Max repetitive peak forward and reverse blocking voltage	V_{DRM}, V_{RRM}	$f = 50$ Hz, $t_p = 10$ ms, $t_{p1} = 250 \mu\text{s}$, $T_{vj} = 5 \dots 125^\circ\text{C}$, Note 1, Note 2	5200		V
Max crest working forward and reverse voltages	V_{DWM}, V_{RWM}	V_{AK}	2600		V
Critical rate of rise of commutating voltage	dv/dt_{crit}	Exp. to 2950 V, $T_{vj} = 125^\circ\text{C}$	2000		V/ μ s



Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Forward leakage current	I_{DRM}	$V_{DRM}, T_{vj} = 125^\circ\text{C}$			500	mA
Reverse leakage current	I_{RRM}	$V_{RRM}, T_{vj} = 125^\circ\text{C}$			500	mA

Note 1: Voltage de-rating factor of 0.11% per $^\circ\text{C}$ is applicable for T_{vj} below $+5^\circ\text{C}$

Note 2: Recommended minimum ratio of V_{DRM} / V_{DWM} or $V_{RRM} / V_{RWM} = 2$. See App. Note 5SYA 2051.

Mechanical data

Maximum rated values ¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Mounting force	F_M		81	90	108	kN
Acceleration	a	Device unclamped			50	m/s^2
Acceleration	a	Device clamped			100	m/s^2

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Weight	m				2.1	kg
Housing thickness	H	$F_M = 90$ kN, $T_a = 25^\circ\text{C}$	26.3		26.7	mm
Surface creepage distance	D_S		36			mm
Air strike distance	D_a		15			mm

1) Maximum rated values indicate limits beyond which damage to the device may occur

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On-state

Maximum rated values ¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Average on-state current	$I_{T(AV)M}$	Half sine wave, $T_c = 70^\circ C$			3875	A
RMS on-state current	$I_{T(RMS)}$				6090	A
Peak non-repetitive surge current	I_{TSM}	$t_p = 10 \text{ ms}, T_{vj} = 125^\circ C, \text{sine wave}$ $\text{after surge: } V_D = V_R = 0 \text{ V}$			55×10^3	A
Limiting load integral	I^2t				15.1×10^6	$A^2\text{s}$
Peak non-repetitive surge current	I_{TSM}	$t_p = 8.3 \text{ ms}, T_{vj} = 125^\circ C, \text{sine wave}$ $\text{after surge: } V_D = V_R = 0 \text{ V}$			60×10^3	A
Limiting load integral	I^2t				14.94×10^6	$A^2\text{s}$

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
On-state voltage	V_T	$I_T = 3000 \text{ A}, T_{vj} = 125^\circ C$			1.54	V
Threshold voltage	$V_{(TO)}$	$I_T = 2300 \text{ A} - 7000 \text{ A}, T_{vj} = 125^\circ C$			1.03	V
Slope resistance	r_T				0.16	$m\Omega$
Holding current	I_H	$T_{vj} = 25^\circ C$ $T_{vj} = 125^\circ C$			125	mA
Latching current	I_L				75	mA
		$T_{vj} = 25^\circ C$ $T_{vj} = 125^\circ C$			500	mA
					250	mA

Switching

Maximum rated values ¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Critical rate of rise of on-state current	di/dt_{crit}	$T_{vj} = 125^\circ C,$ $I_{TRM} = 3000 \text{ A},$ $f = 50 \text{ Hz}$			250	$A/\mu s$
Critical rate of rise of on-state current	di/dt_{crit}				1000	$A/\mu s$
Circuit-commutated turn-off time	t_q	$T_{vj} = 125^\circ C, I_{TRM} = 2000 \text{ A},$ $V_R = 200 \text{ V}, di_T/dt = -1.5 \text{ A}/\mu s,$ $V_D \leq 0.67 \cdot V_{DRM}, dv_D/dt = 20 \text{ V}/\mu s$	700			μs

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse recovery charge	Q_{rr}	$T_{vj} = 125^\circ C, I_{TRM} = 2000 \text{ A},$ $V_R = 200 \text{ V},$ $di_T/dt = -1.5 \text{ A}/\mu s$	3400		5200	μAs
Reverse recovery current	I_{RM}		60		95	A
Gate turn-on delay time	t_{gd}	$T_{vj} = 25^\circ C, V_D = 0.4 \cdot V_{RM}, I_{FG} = 2 \text{ A},$ $t_r = 0.5 \mu s$			3	μs

Triggering

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Peak forward gate voltage	V_{FGM}				12	V
Peak forward gate current	I_{FGM}				10	A
Peak reverse gate voltage	V_{RGM}				10	V
Average gate power loss	$P_{G(AV)}$		see Fig. 9			W

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Gate-trigger voltage	V_{GT}	$T_{vj} = 25^\circ C$			2.6	V
Gate-trigger current	I_{GT}	$T_{vj} = 25^\circ C$			400	mA
Gate non-trigger voltage	V_{GD}	$V_D = 0.4 \times V_{DRM}, T_{vjmax} = 125^\circ C$	0.3			V
Gate non-trigger current	I_{GD}	$V_D = 0.4 \times V_{DRM}, T_{vjmax} = 125^\circ C$	10			mA

Thermal

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Operating junction temperature range	T_{vj}				125	°C
Storage temperature range	T_{stg}		-40		140	°C

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Thermal resistance junction to case	$R_{th(j-c)}$	Double-side cooled $F_m = 81...108 \text{ kN}$			5	K/kW
	$R_{th(j-c)A}$	Anode-side cooled $F_m = 81...108 \text{ kN}$			10	K/kW
	$R_{th(j-c)C}$	Cathode-side cooled $F_m = 81...108 \text{ kN}$			10	K/kW
Thermal resistance case to heatsink	$R_{th(c-h)}$	Double-side cooled $F_m = 81...108 \text{ kN}$			1	K/kW
	$R_{th(c-h)}$	Single-side cooled $F_m = 81...108 \text{ kN}$			2	K/kW

Analytical function for transient thermal impedance:

$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

i	1	2	3	4
$R_i(\text{K/kW})$	3.560	0.680	0.460	0.280
$\tau_i(\text{s})$	0.4069	0.0559	0.0075	0.0018

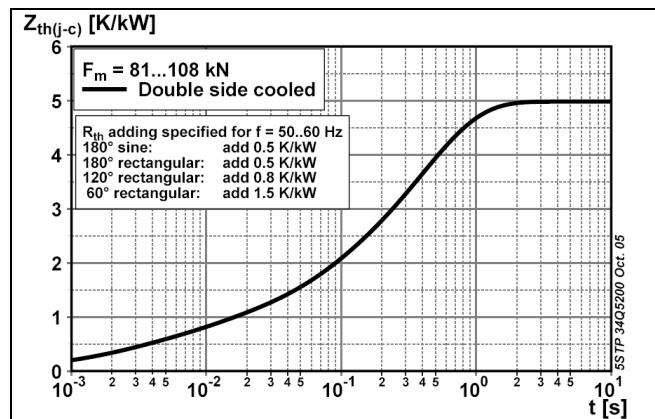


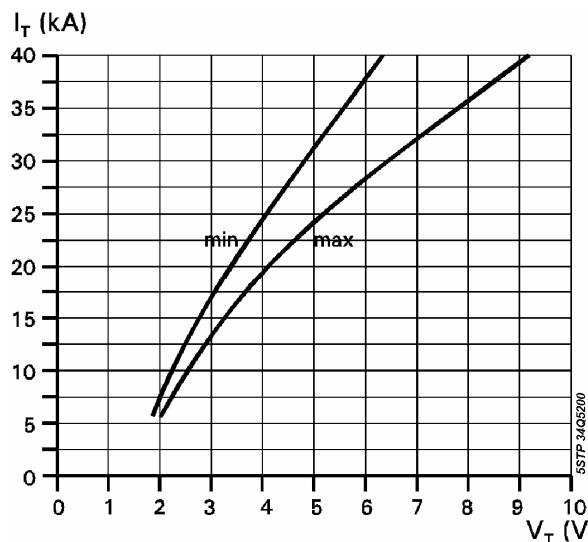
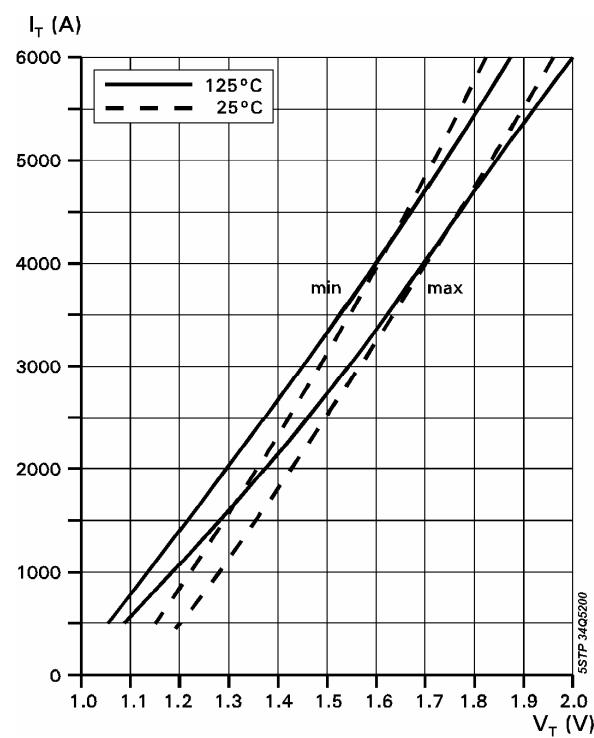
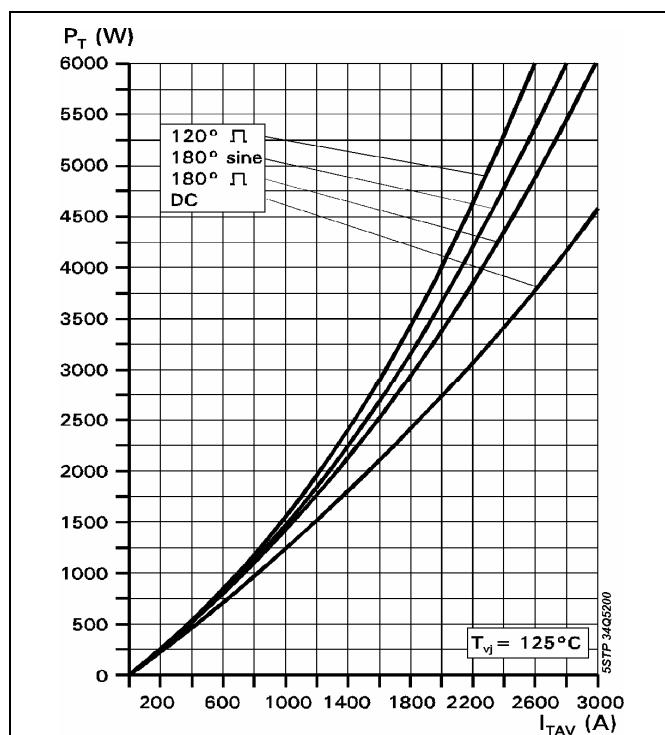
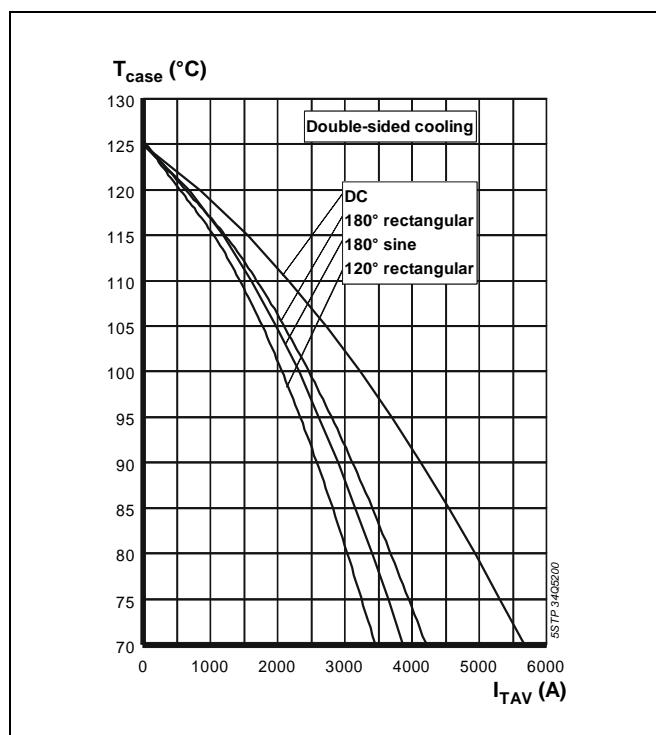
Fig. 1 Transient thermal impedance (junction-to-case) vs. time

On-state characteristic model:

$$V_{T\max} = A + B \cdot I_T + C \cdot \ln(I_T + 1) + D \cdot \sqrt{I_T}$$

Valid for $I_T = 500 - 14000$ A

A	B	C	D
1.065	105.0×10^{-6}	-38.88×10^{-3}	8.155×10^{-3}

**Fig. 2** On-state characteristics, $T_j=125^\circ\text{C}$, 10ms half sine**Fig. 3** On-state voltage characteristics**Fig. 4** On-state power dissipation vs. mean on-state current, turn-on losses excluded**Fig. 5** Max. permissible case temperature vs. mean on-state current, switching losses ignored

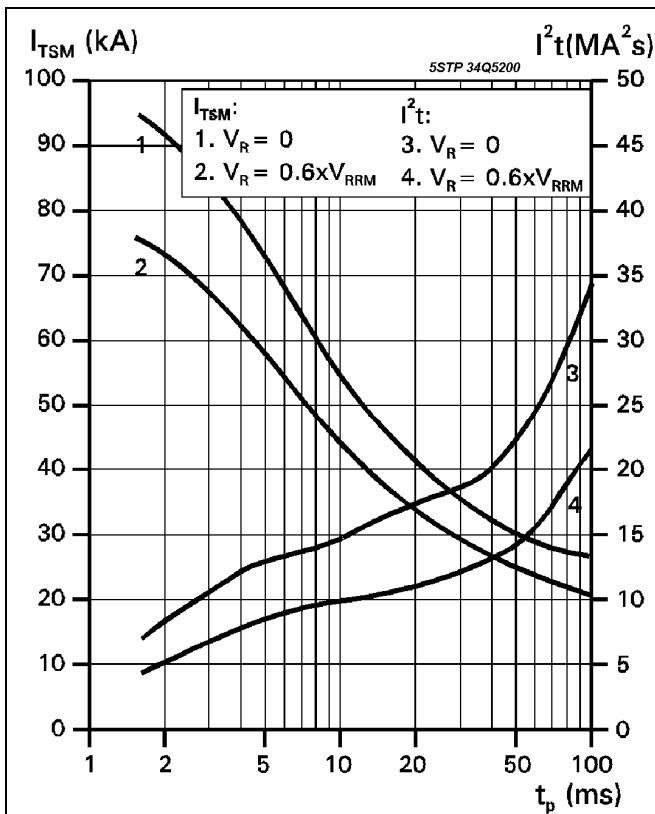


Fig. 6 Surge on-state current vs. pulse length, half-sine wave

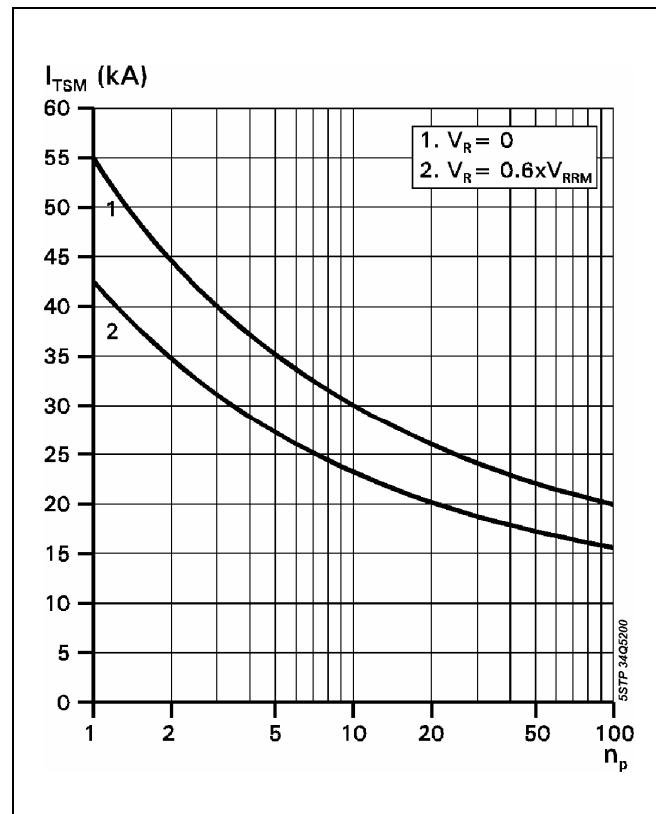


Fig. 7 Surge on-state current vs. number of pulses, half-sine wave, 10 ms, 50Hz

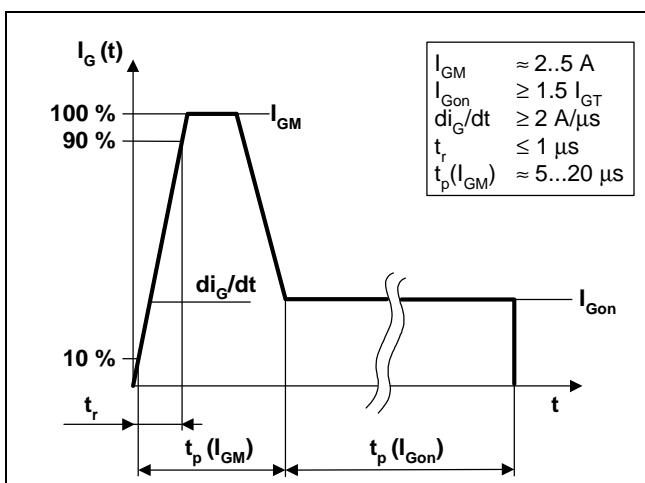


Fig. 8 Recommended gate current waveform

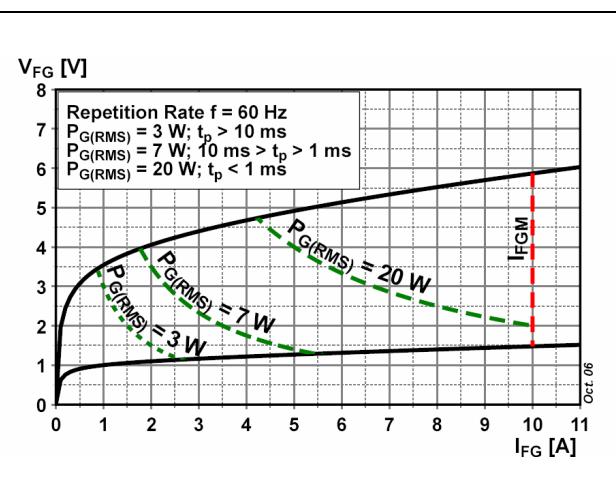


Fig. 9 Max. peak gate power loss

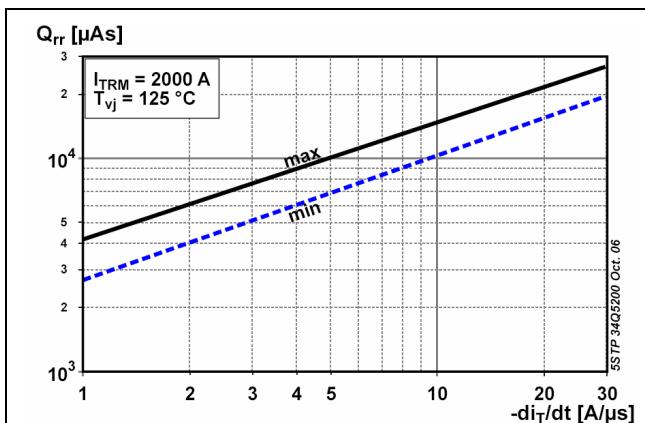


Fig. 10 Reverse recovery charge vs. decay rate of on-state current

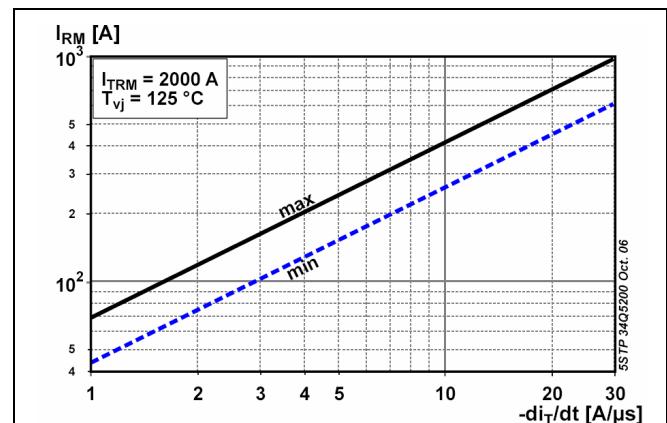


Fig. 11 Peak reverse recovery current vs. decay rate of on-state current

Turn-on and Turn-off losses

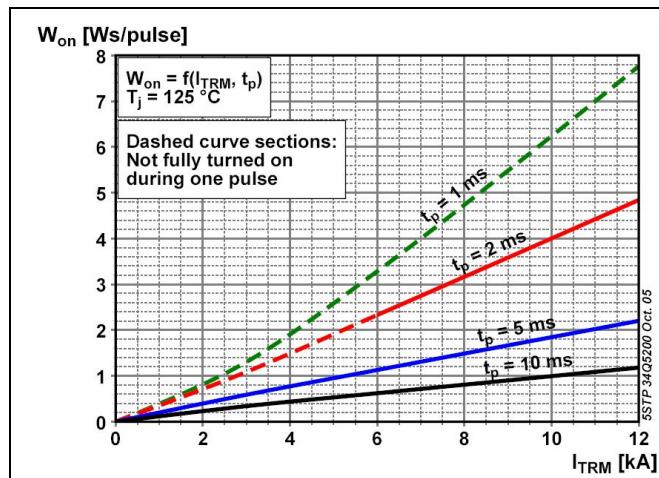


Fig. 12 Turn-on energy, half sinusoidal waves

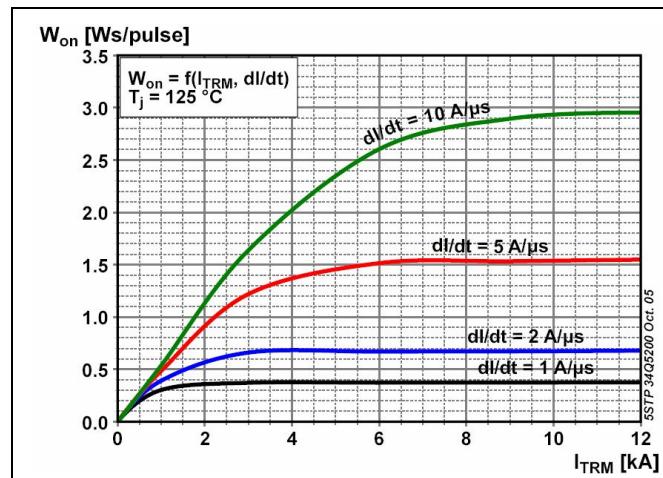


Fig. 13 Turn-on energy, rectangular waves

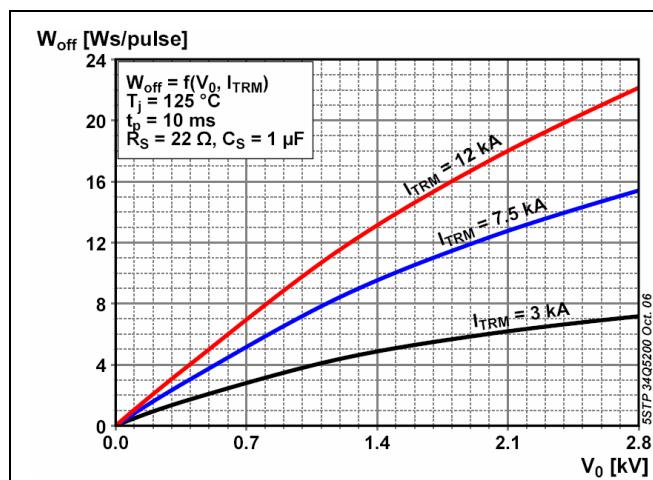


Fig. 14 Turn-off energy, half sinusoidal waves

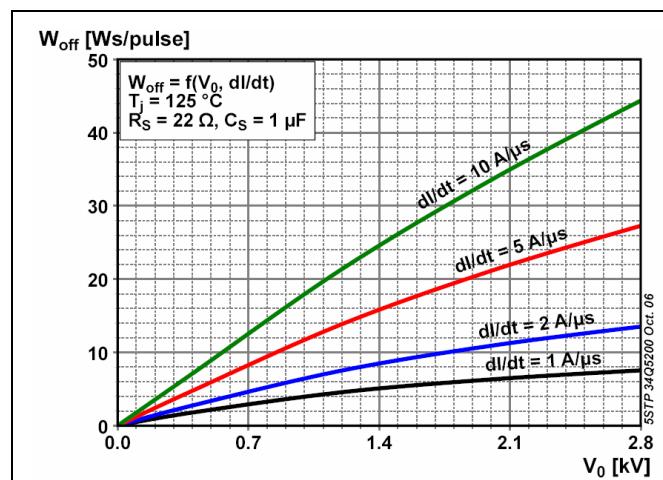


Fig. 15 Turn-off energy, rectangular waves

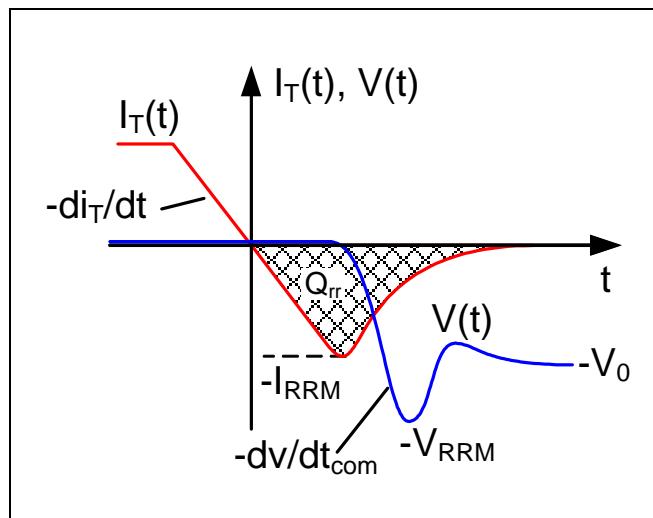


Fig. 16 Current and voltage waveforms at turn-off

Total power loss for repetitive waveforms:

$$P_{TOT} = P_T + W_{on} \cdot f + W_{off} \cdot f$$

where

$$P_T = \frac{1}{T} \int_0^T I_T \cdot V_T(I_T) dt$$

Fig. 17 Relationships for power loss

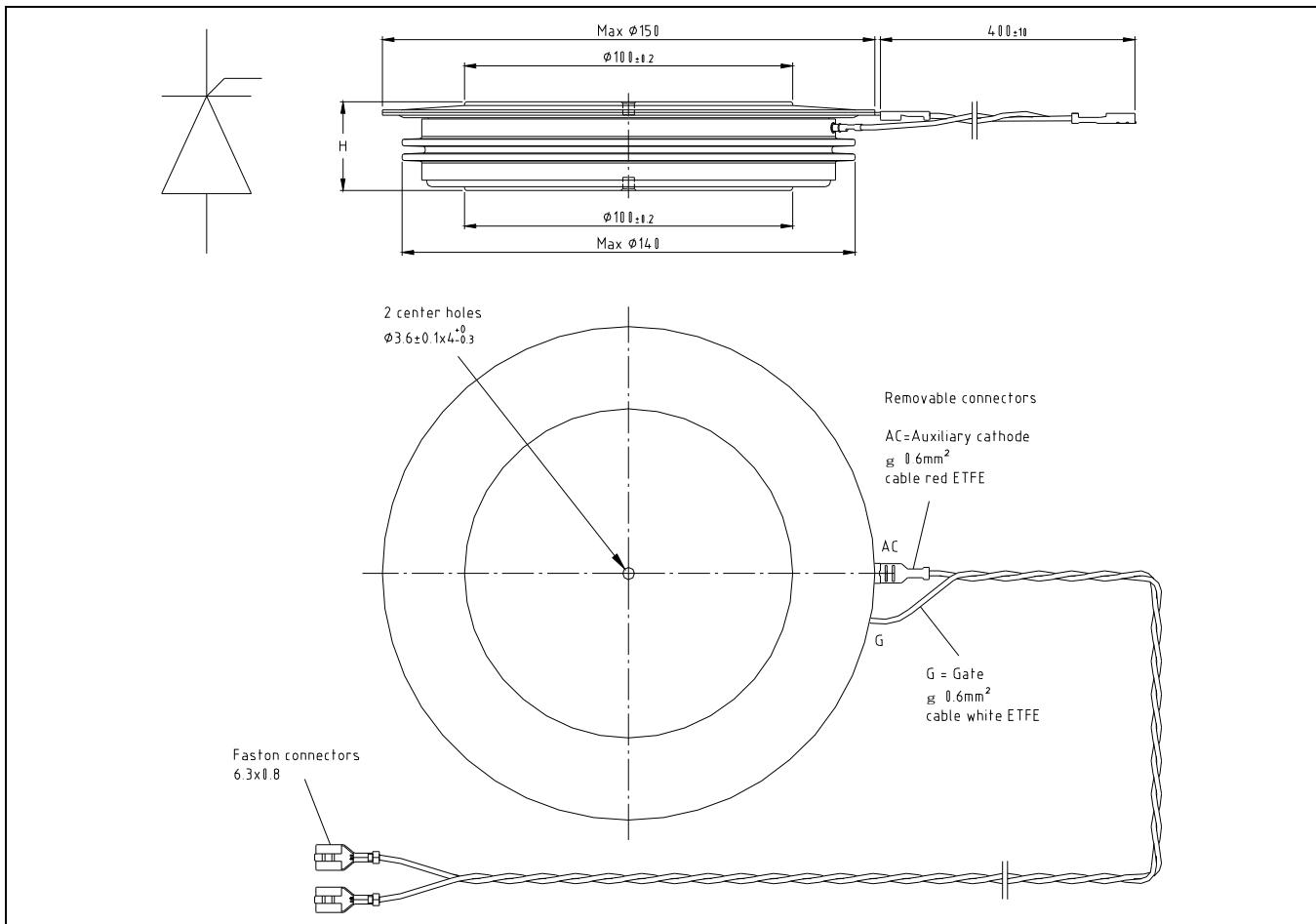


Fig. 18 Device Outline Drawing

Related documents:

- 5SYA 2020 Design of RC-Snubber for Phase Control Applications
- 5SYA 2049 Voltage definitions for phase control thyristors and diodes
- 5SYA 2051 Voltage ratings of high power semiconductors
- 5SYA 2034 Gate-Drive Recommendations for PCT's
- 5SYA 2036 Recommendations regarding mechanical clamping of Press Pack High Power Semiconductors
- 5SZK 9104 Specification of environmental class for pressure contact diodes, PCTs and GTO, STORAGE available on request, please contact factory
- 5SZK 9105 Specification of environmental class for pressure contact diodes, PCTs and GTO, TRANSPORTATION available on request, please contact factory

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